

## Features

- Lead Free Finish/RoHS Compliant (Note1) ("P" Suffix Designates Compliant. See Ordering Information)
- Halogen Free. "Green" Device (Note 2)
- Epoxy Meets UL 94 V-0 Flammability Rating
- Moisture Sensitivity Level 1
- High Surge Current Capability

## Maximum Ratings

- Operating Junction Temperature Range: -55°C to +150°C
- Storage Temperature Range: -65°C to +175°C
- Typical Thermal Resistance(Note 3): 25°C/W Junction to Lead
- Typical Thermal Resistance(Note 3): 80°C/W Junction to Ambient
- Typical Thermal Resistance(Note 3): 22°C/W Junction to Case

MCC Part Number	Device Marking	Maximum Recurrent Peak Reverse Voltage	Maximum RMS Voltage	Maximum DC Blocking Voltage
LMB2S	LB2S	200V	140V	200V
LMB4S	LB4S	400V	280V	400V
LMB6S	LB6S	600V	420V	600V
LMB8S	LB8S	800V	560V	800V
LMB10S	LB10S	1000V	700V	1000V

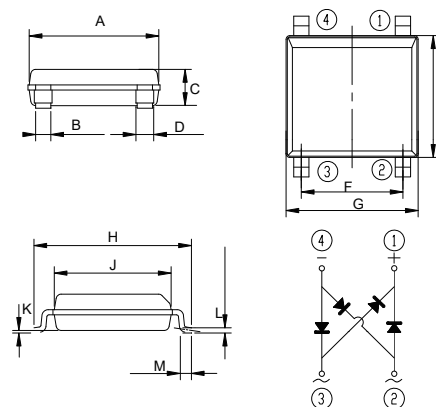
## Electrical Characteristics @ 25°C Unless Otherwise Specified

Average Forward Current	$I_{F(AV)}$	1.0A 0.8A	on Aluminum Substrate; on Glass-epoxy P.C.B
Peak Forward Surge Current	$I_{FSM}$	30A	8.3ms, Half Sine
Maximum Instantaneous Forward Voltage	$V_F$	0.95V	$I_{FM} = 0.4A$ ; $T_J = 25^\circ C$
Maximum DC Reverse Current at Rated DC Blocking Voltage	$I_R$	5 $\mu A$ 100 $\mu A$	$T_J = 25^\circ C$ $T_J = 125^\circ C$
Rating For Fusing	$I^2t$	3.735A <sup>2</sup> s	$t < 8.30ms$
Typical Junction Capacitance	$C_J$	8pF	$V_R = 4V, 1MHz$

- Note: 1. High Temperature Solder Exemption Applied, See EU Directive Annex Notes 7a.  
 2. Halogen free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.  
 3. Device Mounted P.C.B with 0.47x0.47" (12mmx12mm) Copper Pads.

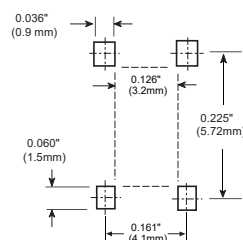
# 1.0 Amp Single Phase Glass Passivated Bridge Rectifier 200 to 1000 Volts

## LMBS-1



DIM	DIMENSIONS				NOTE
	INCHES		MM		
A	0.197	0.205	4.90	5.20	
B	0.024		0.60		
C	---	0.059	---	1.50	
D	0.024	0.032	0.60	0.80	
E	---	0.189	---	4.80	
F	0.150	0.165	3.80	4.20	
G	---	0.209	---	5.30	
H	0.236	0.252	6.00	6.60	
J	0.177	0.185	4.30	4.70	
K	0.0009	0.004	0.02	0.21	
L	0.006	0.012	0.15	0.30	
M	0.017	0.031	0.25	0.80	

### Suggested Solder Pad Layout



**Curve Characteristics**

Fig. 1 - Forward Current Derating Curve

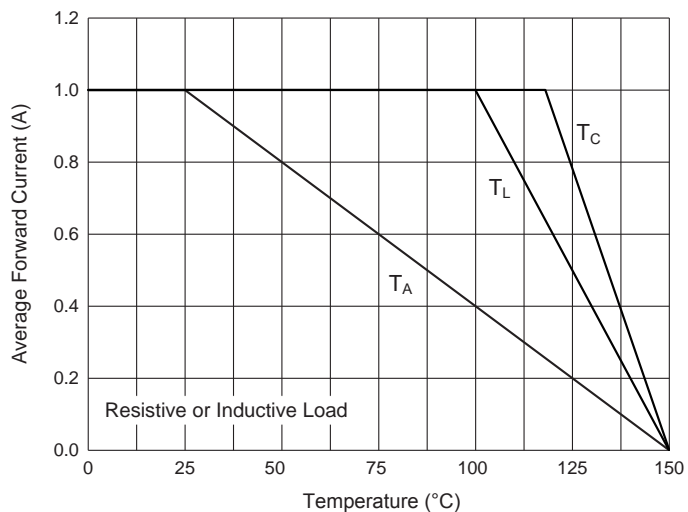


Fig. 2 - Maximum Non-Repetitive Peak Forward Surge Current

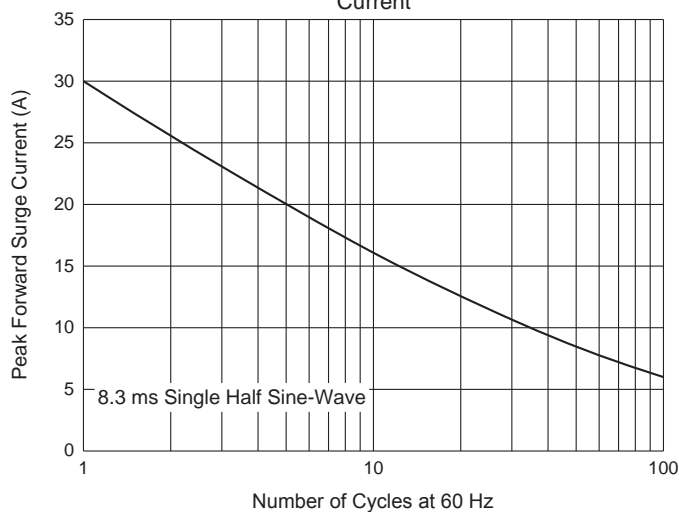


Fig. 3 - Typical Instantaneous Forward Characteristics

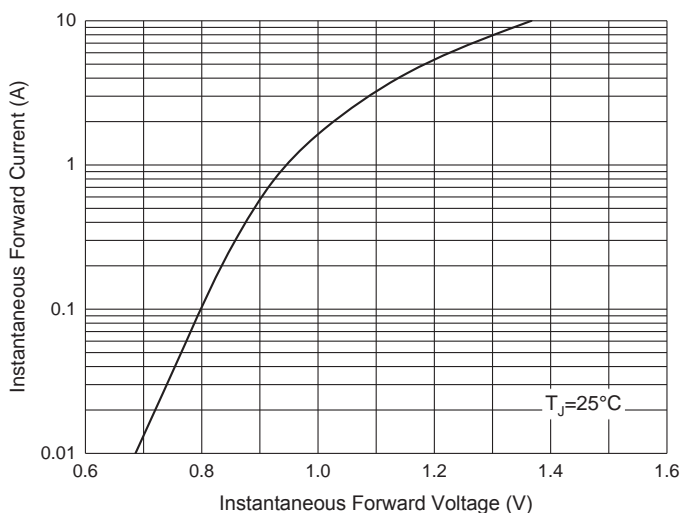


Fig. 4 - Typical Reverse Leakage Characteristics

